

	L #	Hits	Search Text	DBs
1	L1	5394	optic\$2 near inspect\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
2	L2	84178	(defect\$1 or particle\$1 or scratch\$2) near5 (wafers or (integrated near circuit\$1) or ICs or semiconductor\$1 or substrate\$1)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
3	L4	195	1 same 2	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
4	L5	75	time near domain near integrat\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
5	L6	1	4 and 5	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
6	L7	140974 1	(time near delay or integrat\$3) or TDI	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
7	L8	118	4 and 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
8	L9	19022	sens\$3 near3 modul\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
9	L10	8	8 and 9	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
10	L11	11921	(time near delay near integrat\$3) or TDI	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
11	L12	25	4 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
12	L14	420	2 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
13	L16	268	14 and imag\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
14	L17	63	modul\$3 and 16	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
15	L18	12	("4323925" "5065245" "5510618" "5848123" "5872364").pn.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
16	L19	7	("4323925" "4543490" "4810881" "4931647" "5065245" "5159455" "5550380").PN.	USPAT
17	L20	35	4323925.URPN.	USPAT
18	L21	2	20 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
19	L22	4	9 and 20	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B